

Product Texts

LNP THERMOCOMP EC006APQ compound is based on Polyetherimide (PEI) resin containing 30% carbon fiber. Added features of this grade include: Electrically Conductive, High Flow, FAR25.853 Compliant.

Processing/Physical Characteristics	Value	Unit	Test Standard
ASTM Data			
Melt Flow Index, MFI	69	g/10min	ASTM D 1238
Temperature	380	°C	-
Load	6.7	kg	-
Mold Shrinkage, MD	0.2	mm/mm	ASTM D 955
Mold Shrinkage, TD	0.1	mm/mm	ASTM D 955

Mechanical properties	Value	Unit	Test Standard
ISO Data			
Tensile Modulus	29300	MPa	ISO 527
Stress at break	252	MPa	ISO 527
Strain at break	1.1	%	ISO 527
Flexural modulus	23900	MPa	ISO 178
Flexural strength	332	MPa	ISO 178
ASTM Data			
Tensile Modulus	30520	MPa	ASTM D 638
Tensile Strength at Break	281	MPa	ASTM D 638
Elongation at Break	1.2	%	ASTM D 638
Flexural Modulus	26300	MPa	ASTM D 790
Izod Impact notched, 1/8 in	82	J/m	ASTM D 256
Izod Impact unnotched, 1/8 in	713	J/m	ASTM D 256

Thermal properties	Value	Unit	Test Standard
ASTM Data			
DTUL @ 264 psi	195	°C	ASTM D 648

Electrical properties	Value	Unit	Test Standard
ASTM Data			
Surface Resistivity	1000	Ohm	ASTM D 257

Other properties	Value	Unit	Test Standard
Water Absorption, 24hr	0.11	%	ASTM D 570
Density	1390	kg/m ³	ASTM D 792

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	150	°C	-
Pre-drying - Time	4 - 6	h	-
Processing humidity	≤0.02	%	-
Melt temperature	360 - 400	°C	-
Mold temperature	140 - 180	°C	-
Zone 1	360 - 380	°C	-
Zone 2	370 - 390	°C	-
Zone 3	380 - 400	°C	-
Back pressure	0.3 - 0.7	MPa	-

Characteristics**Processing**

Injection Molding

Applications

Automotive

Special Characteristics

Increased electrical conductivity

Regional Availability

North America, Europe, Asia Pacific